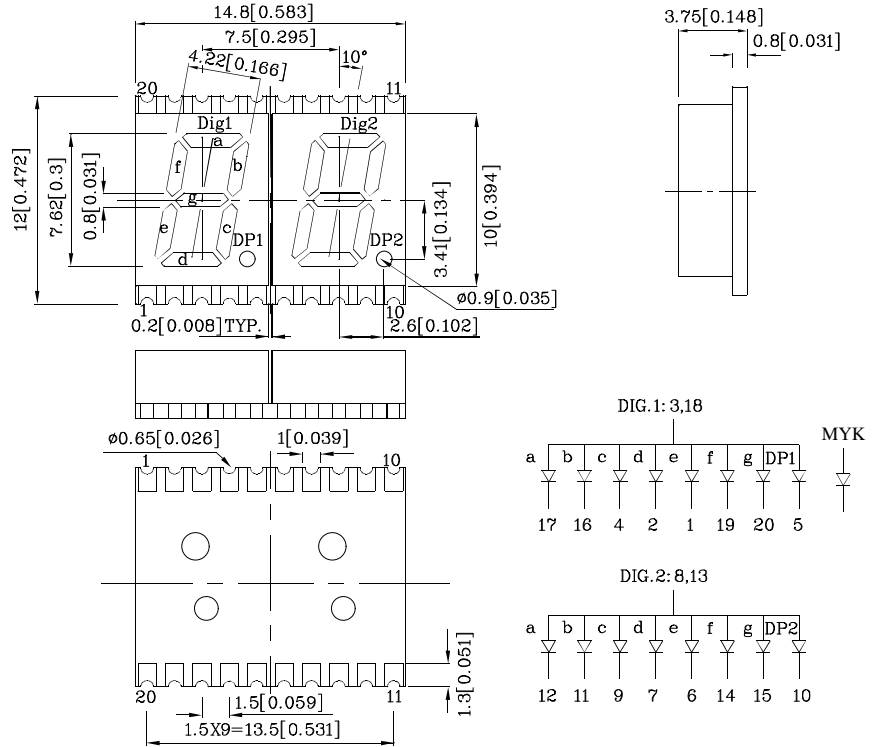


**Features**

- 0.3 inch digit height
- Robust package
- Low power consumption
- Standard configuration: Gray face w/ white segments
- Standard Package: 300pcs/ Reel
- MSL (Moisture Sensitivity Level): 2a
- RoHS Compliant



**Package Schematics**



Notes:

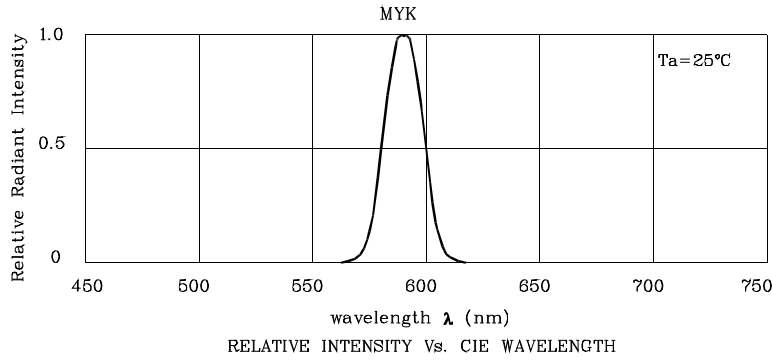
1. All dimensions are in millimeters (inches), Tolerance is ±0.25(0.01") unless otherwise noted.
2. Specifications are subject to change without notice.
3. The gap between the reflector and PCB shall not exceed 0.25mm.

Absolute Maximum Ratings (T <sub>A</sub> =25°C)		MYK (AlGaInP)	Unit
Reverse Voltage	V <sub>R</sub>	5	V
Forward Current	I <sub>F</sub>	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i <sub>FS</sub>	175	mA
Power Dissipation	P <sub>D</sub>	75	mW
Operating Temperature	T <sub>A</sub>	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +85	

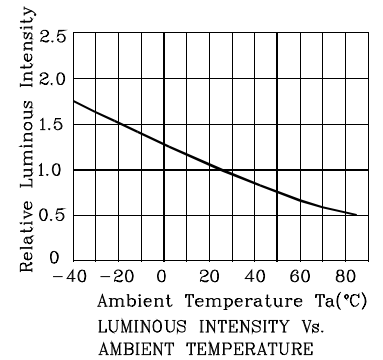
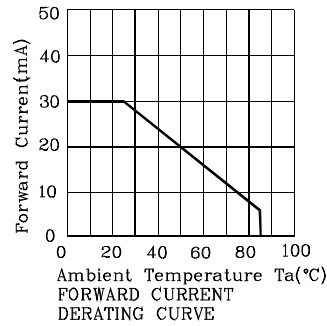
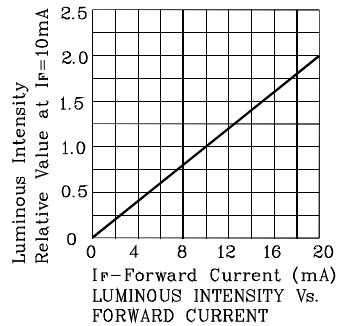
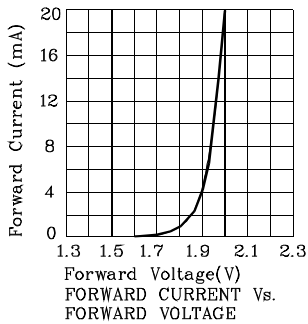
Operating Characteristics (T <sub>A</sub> =25°C)		MYK (AlGaInP)	Unit
Forward Voltage (Typ.) (I <sub>F</sub> =10mA)	V <sub>F</sub>	1.95	V
Forward Voltage (Max.) (I <sub>F</sub> =10mA)	V <sub>F</sub>	2.5	V
Reverse Current (Max.) (V <sub>R</sub> =5V)	I <sub>R</sub>	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I <sub>F</sub> =10mA)	λ <sub>P</sub>	590*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) (I <sub>F</sub> =10mA)	λ <sub>D</sub>	590*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =10mA)	Δλ	20	nm
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	C	20	pF

Part Number	Emitting Color	Emitting Material	Luminous Intensity CIE127-2007* (I <sub>F</sub> =10mA) ucd		Wavelength CIE127-2007* nm λ <sub>P</sub>	Description
			min.	typ.		
XZFMKY07A2	Yellow	AlGaInP	21000 5600*	35990 12990*	590*	Common Anode, Rt.Hand Decimal.

\*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

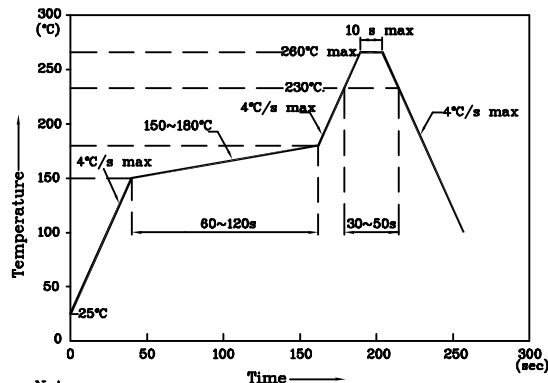


❖ MYK



**LED is recommended for reflow soldering and soldering profile is shown below.**

**Reflow Soldering Profile for SMD Products (Pb-Free Components)**

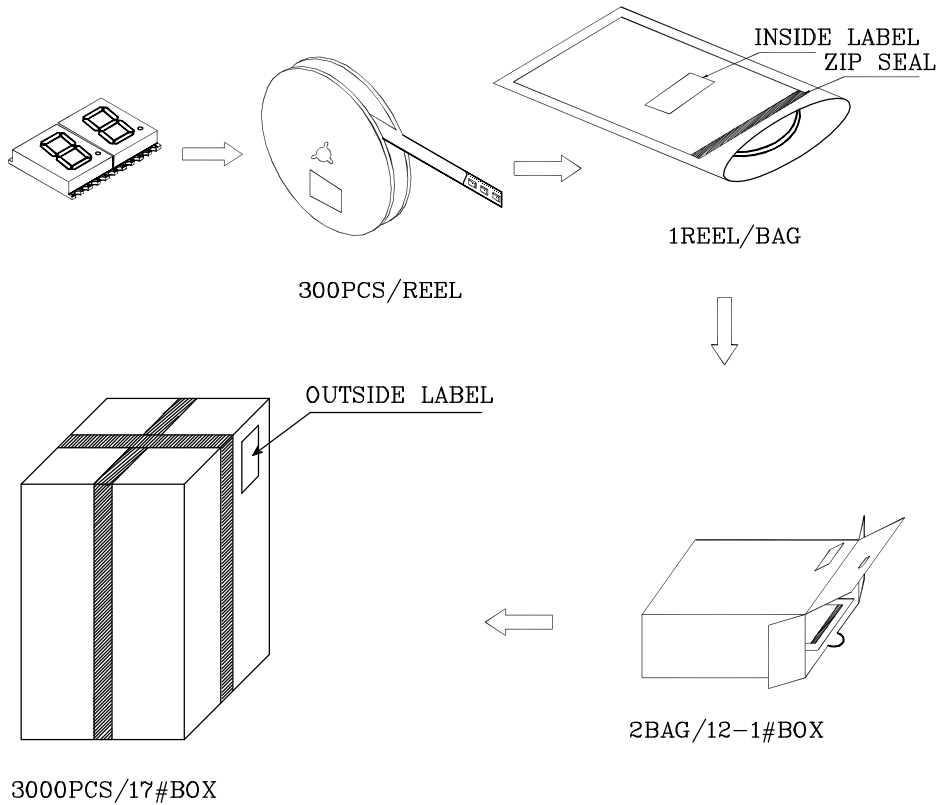


**Notes:**

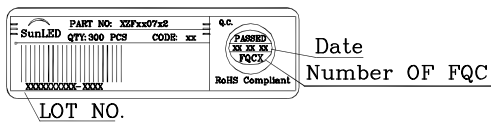
1. Maximum soldering temperature should not exceed 260°C
2. Recommended reflow temperature: 145°C-260°C
3. Do not put stress to the epoxy resin during high temperatures conditions



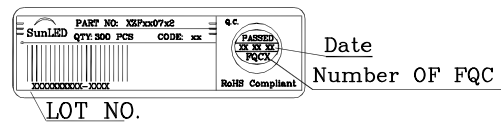
PACKING & LABEL SPECIFICATIONS



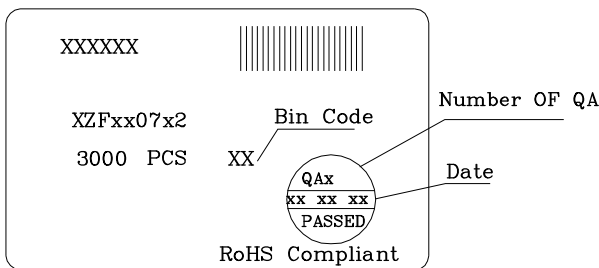
Inside Label On tape



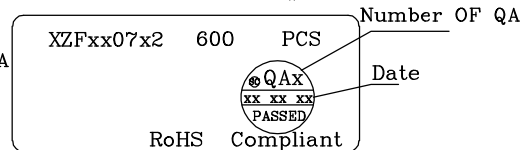
Outside Label On Bag



Outside Label On 17#Box



Outside Label On 12-1#Box



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